

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)			
100	0.018 at V _{GS} = 10 V	70 ^a			

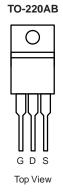
FEATURES

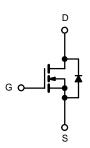
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested



APPLICATIONS

• Isolated DC/DC Converters





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted						
Parameter	-	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V		
Gate-Source Voltage	V _{GS}	± 20	v			
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	ID	70 ^a			
Continuous Diam Current (1) = 173 C)	T _C = 125 °C	O D	35 ^a	\Box A		
Pulsed Drain Current		I _{DM}	145			
Avalanche Current	L = 0.1 mH	I _{AS}	31			
Single Pulse Avalanche Energy ^b	L = 0.1 IIII1	E _{AS}	60	mJ		
Mariana Barra Birata da h	T _C = 25 °C	P _D	355 ^c	W		
Maximum Power Dissipation ^b	T _A = 25 °C ^d	TD T	3.35			
Operating Junction and Storage Temperature Ra	nge	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)		R _{thJC}	0.4	C/VV		

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100		V		
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50		
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.018			
Drain-Source On-State Resistance ^a	r _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}, T_J = 125 ^{\circ}\text{C}$		0.023		Ω	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.037			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b							
Input Capacitance	C _{iss}			1500		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		210			
Reverse Transfer Capacitance	C _{rss}			110			
Total Gate Charge ^c	Qg			90		nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 58 \text{ A}$		23			
Gate-Drain Charge ^c	Q_{gd}			34			
Gate Resistance	R _g		0.5	1.3	3.1	Ω	
Turn-On Delay Time ^c	t _{d(on)}			24	35		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 1.5 \Omega$		220	330	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 58 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5$		45	70		
Fall Time ^c	t _f	Ω		200	300		
Source-Drain Diode Ratings and Cha	aracteristics 7	T _C = 25 °C ^b					
Continuous Current	I _S				70	۸	
Pulsed Current	I _{SM}			115		Α	
Forward Voltage ^a	V _{SD}	I _F = 58 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			130	200	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 30 A, di/dt = 100 A/μs		8	12	Α	
Reverse Recovery Charge	Q _{rr}			0.52	1.2	uС	

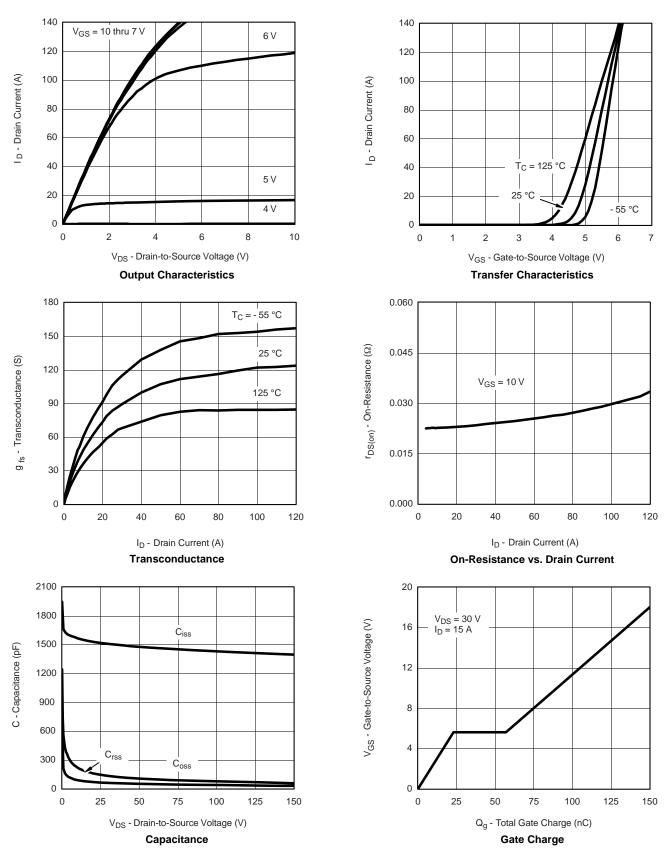
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

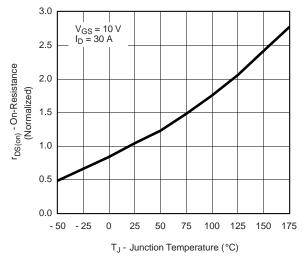


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

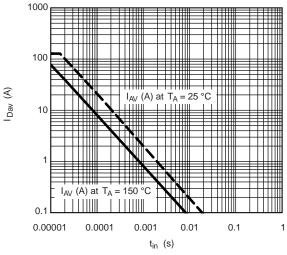




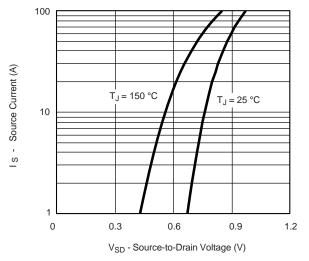
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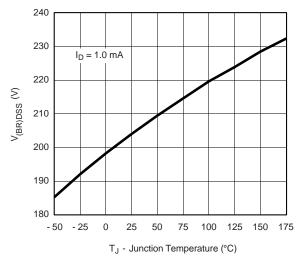
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



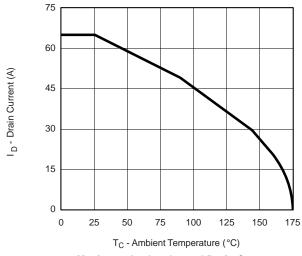
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



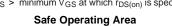
THERMAL RATINGS



r_{DS(on)} Limited 10 µs 100 I_D - Drain Current (A) 10 T_C = 25 °C 10 ms 100 ms DC Single Pulse 0.1 0.1 100 1000 10 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $r_{DS(on)}$ is specified

1000

Maximum Avalanche and Drain Current vs. Case Temperature

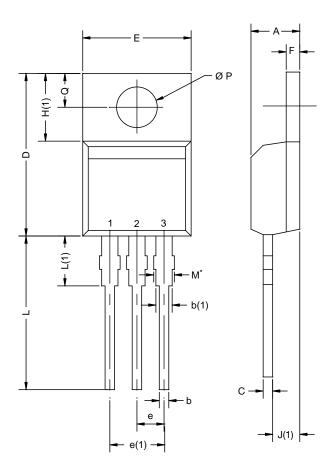




Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



	MILLIM	IETERS	INC	ICHES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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